

EUROPEAN PATENT OFFICE

Patent Abstracts of Japan

PUBLICATION NUMBER : 03229433
PUBLICATION DATE : 11-10-91

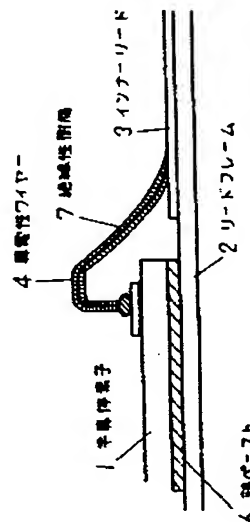
APPLICATION DATE : 02-02-90
APPLICATION NUMBER : 02024931

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INT.CL. : H01L 21/60

TITLE : SEMICONDUCTOR DEVICE



ABSTRACT : **PURPOSE:** To contrive to hold the satisfactory strength of a conductive wire by applying an ultraviolet-curing resin to the conductive wire to be bonded, and by applying ultraviolet ray after bonding to cure the resin.

CONSTITUTION: A semiconductor device 1 is secured to a lead frame 2 by means of silver paste 6, one end of the conductive wire 4 of gold streak is bonded to the electrode or the semiconductor device 1, and the other end of this conductive wire 4 is bonded to the surface of an inner lead 3. The surface of this conductive wire 4 is uniformly coated with an insulating resin 7 and an ultraviolet radiation curing acrylic adhesive resin is used as the insulating resin 7. The adhesive resin is liquid and uniformly applied to the surface of the conductive wire during bonding of the conductive wire. After the end of bonding, ultraviolet ray is applied to cure the adhesive resin. The cured resin holds mechanical strength and electrical insulating properties.

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